

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Takashi HIRAGA et al.

Attn: PCT Branch

Application No. 09/913,315

Filed: August 10, 2001

Docket No.: 110345

For: MODIFICATION METHOD OF SURFACE LAYER OF MOLDED RESIN  
ARTICLE, AND MODIFICATION APPARATUS OF SURFACE LAYER OF  
MOLDED RESIN ARTICLE

SUPPLEMENTAL PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office  
Washington, D. C. 20231

Sir:

Prior to initial examination, and after entry of the Annexes to the IPER, please amend  
the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 27 and 29 without prejudice to or disclaimer of the subject matter  
contained therein.

Please add new claims 46-63 as follows:

--46. The modification method of the resin surface layer according to claim 6 wherein:

the vapor of the organic compound is uniformly deposited on the surface of the  
molded resin article; and

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in order to allow the deposited organic compound to penetrate/disperse for the  
surface of the molded resin article into its inside,

the temperature of the molded resin article is raised up to a temperature which  
is equal to or higher than a glass transition temperature of the resin and which does not  
exceed the thermal decomposition temperature of the organic compound and/or the resin.--